

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A circuit board manufacturing method, comprising:
forming a transfer chip, the forming of the transfer chip including:
forming a wiring above a first substrate,
forming a plurality of first pad electrodes so as to be connected to the
wiring and so as to be included in the transfer chip, and
joining the transfer chip with a member such that the plurality of first
pad electrodes contact the member.
~~forming, on a first substrate, a transfer chip including a thin film electrical~~
~~circuit formed of stacked films and a plurality of first pad electrodes used as connection~~
~~terminals to establish connections between the thin film electrical circuit and another circuit;~~
~~forming a second substrate including electrical circuit wiring and a plurality of~~
~~second pad electrodes connected to the electrical circuit wiring and arranged in a transfer~~
~~target region, the second pad electrodes being respectively associated with the first pad~~
~~electrodes provided on the transfer chip; and~~
~~transferring the transfer chip on the first substrate to the transfer target region~~
~~on the second substrate to connect the thin film electrical circuit to the electrical circuit~~
~~wiring, thereby forming a circuit board;~~
~~the first pad electrodes being arranged over the entire surface of the transfer~~
~~chip and covering at least one of thin film elements and thin film wiring included in the thin~~
~~film electrical circuit provided below the first pad electrodes, tops of rough surface portions~~
~~of the pad electrodes having approximately the same height.~~

2. (Currently Amended) The circuit board manufacturing method according to claim 1, each of the plurality of first pad electrodes having a plurality of first portions, one of the plurality of first portions being located a greatest distance away from a bottom of the transfer chip, and the greatest distance substantially coinciding with the plurality of first pad electrodes, ~~further including adjusting the heights of the tops of the rough portions of the first pad electrodes by adding height adjusting films when forming the thin film elements or the thin film wiring.~~

3. (Currently Amended) The circuit board manufacturing method according to claim 1, further comprising:

forming the member, the forming of the member including:
forming a second substrate,
forming electrical circuit wiring above the second substrate, and
forming a plurality of second pad electrodes so as to be connected to
the electrical circuit wiring and arranged in a transfer target region, the second pad electrodes
being respectively associated with the plurality of first pad electrodes provided on the transfer
chip, ~~the forming of the second substrate including forming the second pad electrodes to cover~~
~~the electrical circuit wiring provided therebelow, whereby the tops of rough surface portions~~
~~of the second pad electrodes have approximately the same height.~~

4. (Currently Amended) The circuit board manufacturing method according to claim 32, further comprising:

adjusting a distance of at least one of the plurality of first portions of each of
the first pad electrodes from the bottom of the first substrate by adding distance adjusting
films when forming the transfer chip, ~~further including adjusting the heights of the tops of the~~
~~rough portions of the second pad electrodes by adding height adjusting films when forming~~
~~the electrical circuit wiring.~~

5. (Currently Amended) The circuit board manufacturing method according to claim +3, forming the plurality of second pad electrodes so as to cover the electrical circuit wiring, each of the plurality of second pad electrodes having a plurality of second portions, one of the plurality of second portions being located a greatest distance away from a bottom of the second substrate, the greatest distance substantially coinciding with the plurality of second pad electrodes.

~~the first pad electrodes having the same film structure of the stacked films in regions associated with the tops.~~

6. (Currently Amended) The circuit board manufacturing method according to claim +5, further comprising:

adjusting a distance of at least one of the plurality of second portions of each of the second pad electrodes from the bottom of the second substrate by adding distance adjusting films when forming the member.~~the second pad electrodes having the same film structure of the lower stacked films in regions associated with the tops.~~

7. (Currently Amended) ~~A~~The circuit board manufacturing method, according to claim 1, comprising:the plurality of first pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of first portions of each of the first pad electrodes from a bottom of the transfer chip.

~~forming, on a first substrate, a transfer chip including a thin film electrical circuit formed of stacked films and a plurality of first pad electrodes used as connection terminals to establish connections between the thin film electrical circuit and another circuit;~~

~~forming a second substrate including electrical circuit wiring and a plurality of second pad electrodes connected to the electrical circuit wiring and arranged in a transfer target region, the second pad electrodes being respectively associated with the first pad electrodes provided on the transfer chip; and~~

~~transferring the transfer chip on the first substrate to the transfer target region on the second substrate to connect the thin film electrical circuit to the electrical circuit wiring, thereby forming a circuit board;~~

~~the first pad electrodes being arranged over the entire surface of the transfer chip and covering at least one of thin film elements and thin film wiring included in the thin film electrical circuit provided below the first pad electrodes;~~

~~the second pad electrodes being arranged over the entire transfer target region so as to be associated with the arrangement of the first pad electrodes and covering the electrical circuit wiring provided therebelow, and~~

~~the first pad electrodes and the second pad electrodes being formed so that the sums of the heights of tops of rough surface portions of pairs of the first and second pad electrodes facing each other are approximately constant.~~

8. (Currently Amended) The circuit board manufacturing method according to claim 13, the plurality of second pad electrodes having a film structure that is the same as a film structure in regions associated with a greatest distance of a plurality of second portions of each of the second pad electrodes from a bottom of the second substrate.~~the transferring including forming adhesive layers between the first pad electrodes provided on the transfer chip and the second pad electrodes provided on the second substrate.~~

9. (Currently Amended) The circuit board manufacturing method according to claim 1, further comprising:

connecting one first portion of a plurality of first portions of one first pad electrode of the plurality of first pad electrodes to one second portion of a plurality of second portions of one second pad electrode of a plurality of second pad electrodes; and

connecting one first portion of the plurality of first portions of another first pad electrode of the plurality of first pad electrodes to one second portion of the plurality of second portions of another second pad electrode of the plurality of second pad electrodes,
a distance between a bottom of the transfer chip and a bottom of the second substrate through the one first pad electrode and the one second pad electrode coinciding with a distance through the another first pad and the another second pad electrode.~~the forming the transfer chip including forming an ablation layer between the first substrate and the transfer chip, the ablation layer having a characteristic such that the adhesiveness with respect to the transfer chip is weakened due to a change of state in response to application of energy.~~

10. (Currently Amended) The circuit board manufacturing method according to claim 3, the joining of the transfer chip with the member including forming adhesive layers between the first pad electrodes provided on the transfer chip and the second pad electrodes provided on the second substrate.~~A transfer chip serving as a transfer unit, the transfer chip being formed on a first substrate and transferred from the first substrate to a second substrate having wiring, the transfer chip comprising:~~

~~at least a thin film electrical circuit formed of stacked films; and~~
~~a plurality of pad electrodes to establish connections between the thin film electrical circuit and another circuit, the pad electrodes being arranged over the entire surface of the transfer chip and covering at least one of thin film elements and thin film wiring included in the thin film electrical circuit provided below the pad electrodes, tops of rough surface portions of the pad electrodes having approximately the same height.~~

11. (Currently Amended) The circuit board manufacturing method according to claim 1, the forming of the transfer chip including forming an ablation layer between the first substrate and the transfer chip, the ablation layer having a characteristic such that the

adhesiveness with respect to the transfer chip is weakened due to a change of state in response to application of energy. ~~A transfer source substrate, comprising:~~

~~————— a plurality of the transfer chips as set forth in claim 10, the plurality of the transfer chips being arranged on a substrate.~~

12. (Currently Amended) A transfer chip serving as a transfer unit manufactured by the method of claim 3. ~~The transfer source substrate according to claim 11, further comprising an ablation layer between the substrate and the transfer chips, the ablation layer having a characteristic such that the adhesiveness with respect to the transfer chips is weakened due to a change of state in response to application of energy.~~

13. (Original) An electro-optical device manufactured using a circuit board manufactured by the manufacturing method as set forth in claim 1.

14. (Original) An electronic apparatus, comprising:

the electro-optical device as set forth in claim 13 usable as a display unit.